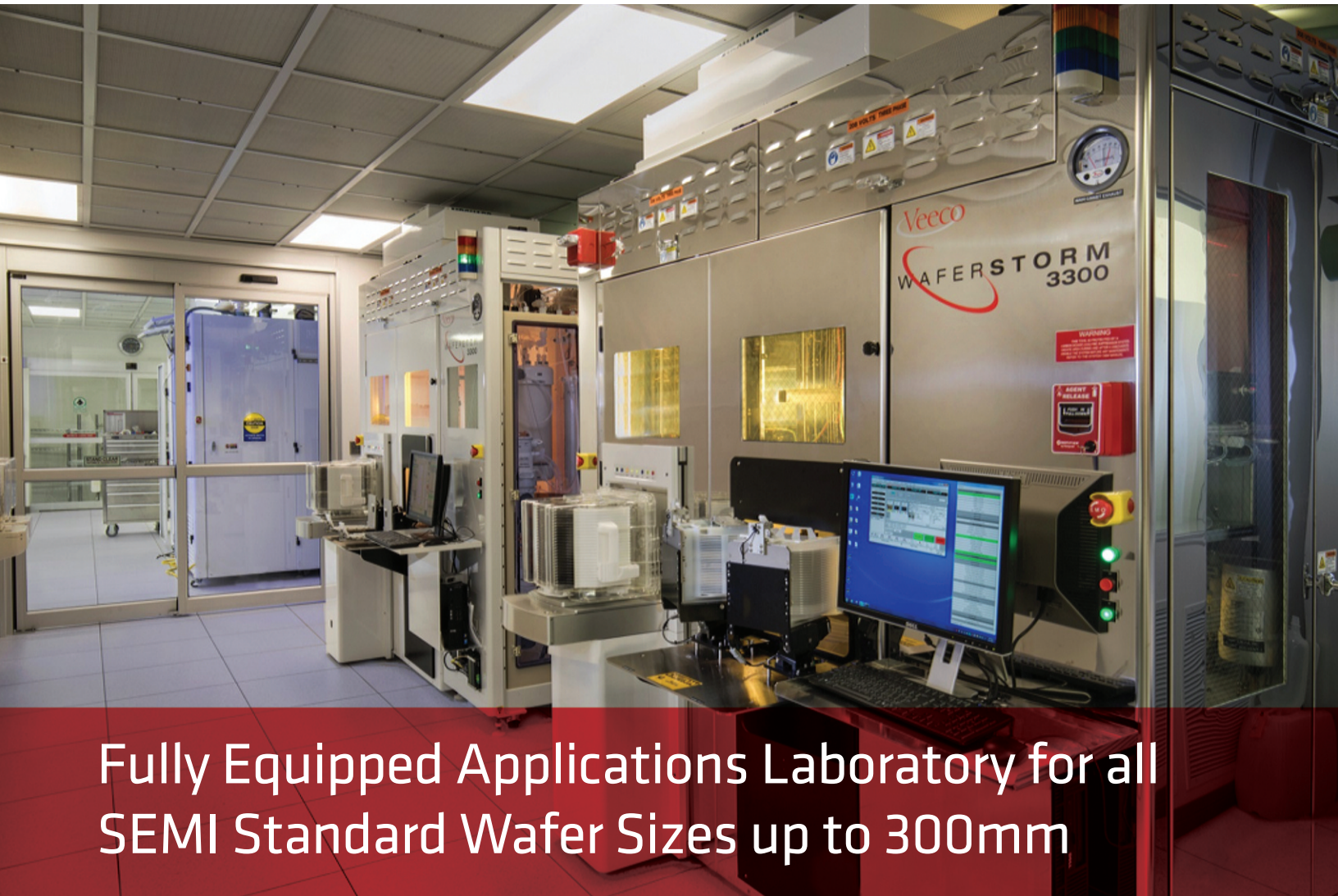


# World-Class Laboratory Capabilities from a Leader in Single Wafer Wet Process Technology



Fully Equipped Applications Laboratory for all SEMI Standard Wafer Sizes up to 300mm

Aiding our customers in the development and support of their manufacturing processes with an extensive suite of single wafer processors including:

- > Cleaning processors
- > Solvent processors
- > Etch processors
- > Developer



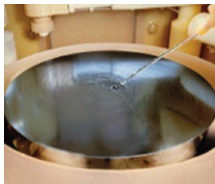
Precision Surface Processing

## Veeco Precision Surface Processing Advantage

Veeco's Horsham, Pennsylvania facility features a fully equipped, state-of-the-art applications laboratory and a highly trained technical staff. Learn how Veeco's dedicated team of single wafer experts and over 50 years of global install base experience can advance your process performance.

Capabilities include:

### CLEANING



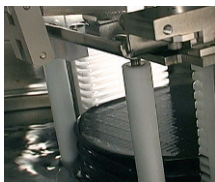
Cleaning capabilities for the most challenging FEOL (front end of line) and BEOL (back of end line) semiconductor customer requirements. Capabilities include single-sided and double-sided PVA brush scrubbing, high velocity spray, high pressure spray and single-wafer megasonics. Dilute chemistries can be mixed by recipe using PC programmable, point-of-use chemical blending.

### ETCH



Veeco's single wafer technology achieves outstanding wet etch performance. Veeco's patented WaferChek® in-situ process monitor provides endpoint detection for a wide variety of materials such as metals, oxides and semiconductors.

### SOLVENT



Veeco's ImmJET™ technology delivers precise control of wafer environments and chemical temperature to strip photoresist, remove post-etch polymer residues and dissolve polymers used in material lift-off processes. Thick dry film resists and flux can also be stripped using this combined capability. The use of high pressure fan spray completely removes residues in a timely manner.



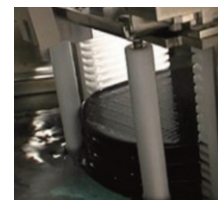
*Veeco Precision Surface Processing invests significantly in our customer's success. Our applications lab features metrology and process equipment ready to take your production performance to the next level.*

## Veeco's Applications Laboratory maintains metrology equipment on-site to provide immediate feedback and support.

- > Hitachi 3700N Scanning Electron Microscope with IXRF EDX Microanalysis
- > Hitachi SU5000 Field Emission SEM
- > Hitachi IM4000 Ion Mill System for cross-sectioning
- > KLA-Tencor SP2 Particle Inspection to 32nm (300mm wafers)
- > KLA-Tencor Candela CS10 Optical Surface Analyzer
- > KLA P16 Surface Profilometer
- > Bruker Icon Atomic Force Microscope
- > Filmetrics F60-t Ellipsometer
- > Sentronics Wafer Thickness Measurement System
- > Olympus LEXT Confocal Laser Scanning Microscope
- > Signatone QuadMap 4-Point Probe Resistivity Measurement

### At A Glance

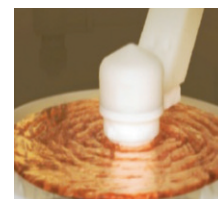
- > **50 YEARS**  
Leader in single wafer wet process equipment
- > **Global Customer Installed Base**
- > **50-450 MM**  
Wafer size capability
- > **2 SYSTEMS**  
WaferStorm® / WaferEtch®  
Flexible / Configurable
- > **1-8 CHAMBERS**  
Throughput matched to customer requirements



Solvent



Etch



Clean

**Learn more about Veeco's single wafer process capabilities at [www.veeco.com/PSP](http://www.veeco.com/PSP)**

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**Precision Surface Processing**